

# **Project Ideas from European brokerage event of February 18-19 (Brussels)**

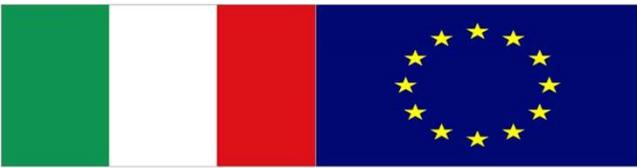
## ***“Chips JU 2025 Non Initiative Call”***

Alberto Bianchi,

Chips JU SRIA 2025, INSIDE Industry Association (Leonardo S.p.A)

Livio Baldi,

President Chips Mirror Group Italy



# ECS Brokerage Event



All Presentations at ECS brokerage event 2025 are available at:

<https://ecs-brokerage-event.eu/delegate-page/>

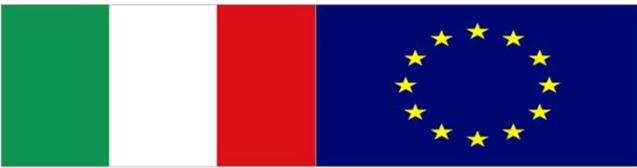
ECS collaboration Tools can be accessed from here, or directly at:

<https://ecscollaborationtool.eu/>

Login at your account. If you do not have it, you can create it here.

It is FREE!

The image shows two overlapping website screenshots. The top screenshot is for the 'ECS BROKERAGE EVENT 2025' held on 18 & 19 February. It features a navigation menu with 'Overview', 'Participation', 'Venue', and 'Contact'. Logos for 'Aeneas', 'EPoSS' (European Association for Smart Hydrogen Integration), and 'INSIDE' (Industry Association) are visible on the right. The bottom screenshot is for the 'ECS COLLABORATION TOOL'. It has a navigation menu with 'About', 'Features', 'Resources & Events', and 'Get Started'. The main heading is 'Collaborate and Innovate with ECS'. Below it, a description states: 'The ECS Collaboration Tool is a platform to create project proposals and connect with partners in the field of Electronic Components and Systems.' There are two buttons: 'Get Started' and 'Create an Account'. The 'Create an Account' button is highlighted with a red box, and a red arrow points from the text 'you can create it here.' to it. A red line also connects the text 'Login at your account...' to the 'Log In' button.



# ECS Collaboration Tool



**ECS COLLABORATION TOOL**  
ECS Collaboration Tool – Simple Mode

Create a Project Idea   My Ideas   Browse Ideas   Download Project Ideas (Excel)   My profile   Logout   **Switch to Advanced Mode**

You can use the Advanced Mode to insert filters

**Browse Ideas**

Search by project idea name, acronym, keyword or inside the descriptions

46 items on 6 pages

Fav	Project idea	Acronym	Contact	Organisation	Created	Keywords
	<a href="#">TrustLine</a>	Trust Factor Coefficient Based Dynamic Product Line Acceleration Mechanism for Intelligent Systems	Muhammed Akif AĞCA	TOBB ECONOMY AND TECHNOLOGY UNIVERSITY (TOBB ETU) (TUR)	2024-01-17	<a href="#">Cyber intelligence</a> · <a href="#">Distributed computing</a> · <a href="#">Stream processing</a> · <a href="#">Middleware</a> · <a href="#">Trusted computing</a>

TrustLineTrust Factor Coefficient Based Dynamic Product Line Acceleration Mechanism for Intelligent Systems

**Search**   **Reset**

**ECS SRIA** ⓘ

**Chapters**

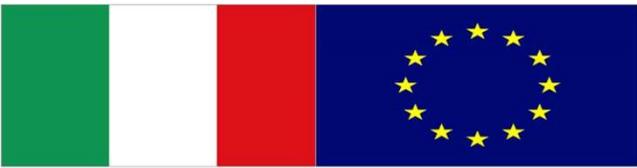
- 1.2 Componentss, Modules and System Integration [20]
- 1.1. Process Technology, Equipment, Materials & Manufacturing for ECS [16]

**Events**

- ECS Brokerage 2025 [46]
- ECS Brokerage 2024 [42]

**Keywords**

- Ai [3]
- Chip [3]
- Robotics [3]



# ECS Collaboration Tool



49 items on 7 pages

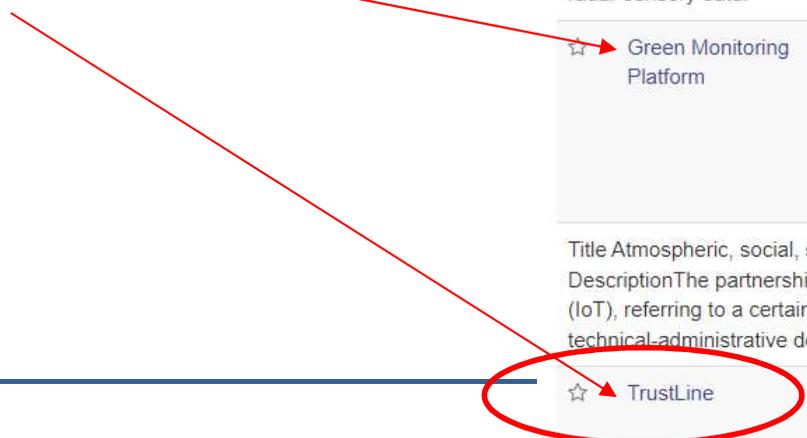
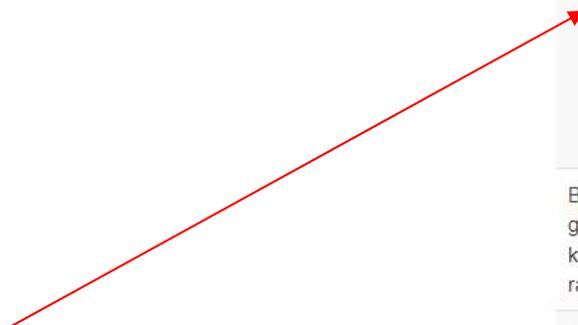
Search Reset

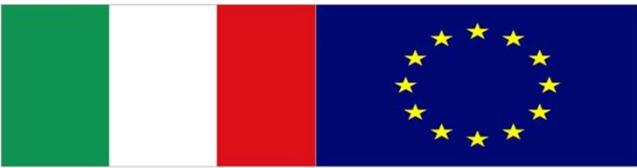
Fav	Project idea	Acronym	Contact	Organisation	Created	Keywords
☆	Developing projects for the production and fleet management	Developing Projects for the production and fleet management of agv robots in smart factories, smart	FARUK TATAŞ	MODOYA Elektronik Otomasyon Mühendislik Danışmanlık San. ve (TUR)	2024-02-01	Autonomous vehicles · Agv · Amr · Robots · Smart factory
☆	PROCCEPTION	Near-/In-sensor processing for next-generation perception systems	Edgars Lielamurs	Institute of Electronics and Computer Science (LVA)	2024-02-12	Sensor integration · Machine vision · Neuromorphic computing
☆	Green Monitoring Platform	Atmospheric, social, strategic, economic and green environmental impact monitoring	Gianluca Rossi	Ro Technology srl (ITA)	2024-02-14	Machine learning · Deep learning · Image processing · IoT applications · Data analysis
☆	TrustLine	Trust Factor Coefficient Based Dynamic Product Line Acceleration	Muhammed Akif AĞÇA	TOBB ECONOMY AND TECHNOLOGY UNIVERSITY (TUR)	2024-01-17	Cyber intelligence · Distributed computing · Stream processing · Middleware · Trusted computing

- 1.2 Componentss, Modules and System Integration [30]
- 2.1 Edge Computing and Embedded AI [27]
- 2.4 Quality, Reliability, Safety and Cyber-Security [22]
- 1.3 Embedded Software and Beyond [20]
- 1.1. Process Technology, Equipment, Materials & Manufacturing for ECS [19]
- 1.4 System of Systems [17]
- 3.3. Digital Industry [16]
- 2.3. Architecture and Design: Method and Tools [15]
- 3.1 Mobility [15]
- 2.2. Connectivity [13]
- 3.6 Digital Society [11]
- 3.4 Health and Well-Being [10]
- 3.5 Agrifood and Natural Resources [7]
- 3.2. Energy [6]

- Events**
- ECS Brokerage 2024 [49]
  - ECS Brokerage 2023 [46]
  - KDT kick off and

For more detailed descriptions and for downloading poster and/or pitch





# ECS Collaboration Tool



Description



Sought Partners



Involved Partners



If interested leave a comment to the coordinator



☆ PROJECT IDEA TRUSTLINE

Trust Factor Coefficient Based Dynamic Product Line Acceleration Mechanism for Intelligent Systems

Short Description  
TrustLine Trust Factor Coefficient Based Dynamic Product Line Acceleration Mechanism for Intelligent Systems

Key Selling Points  
Market need: Increasing number of nodes and diversity on components in growing intelligent systems require dynamic holistic views and trusted scalable system/data models to ensure (near) real-time functionalities. Innovation: Trust factor coefficient based dynamic holistic views enables to manage edge nodes and enable to build end-to-end holistic abstractions for the dynamic requirements of the use-case domains of trusted AI systems. Software driven hardware designs with trust factor coefficient based accelerated product line mechanisms. Business Impact: Growing AI systems will have trusted 5G connectivity at massive scale to ensure (near) real-time functionality of the system and enable intracountry smart-city experimentalizations. See for details for initial DigBank 5G Connected Hybrid-Cloud smart-city experiments with improved Chip-set designs, have trusted computing features at any scale: <https://oexplore.ieee.org/abstract/document/10273674>, Trusted Distributed Artificial Intelligence (TDAI)

Already Involved

- Partners Involved
- Full stack system architects
- Researcher/hardware designer for 5G Connected communication channels.
- TOBB ECONOMY AND TECHNOLOGY UNIVERSITY (TOBB ETU)
- Safiran Electronics and Defense Spain
- emotion3D
- Aerospac Valley
- V-Research GmbH
- Politecnico di Milano
- Altek S.p.A.
- Satcom Mobility System SAS
- UEF (University of Eastern Finland)
- Telecom Paris
- RISE Research Institutes of Sweden AB
- Excellum AB
- Università degli Studi dell'Aquila
- NXP Semiconductors France
- Biorseyes Community association
- TheProWow.Me Ltd
- University of Turkish Aeronautical Association
- Yongstak Microelectronics
- Siemens Advanta Development
- Birmingham City University
- Aalto University
- KnowL solutions BV
- KU Leuven
- Instituto de Telecomunicações
- Bewell Teknoloji San.Tic.A.Ş.
- B4Future

Looking for

Partners needed:  
Expertise: Use-case experiments of smart-cities  
Partner type: Any interested legal entity.  
Countries: Türkiye, EU, USA and other interested countries.

Select other idea  
TrustLine - Trust Factor Coefficient Based Dynam

Programme calls

- Chips-JU Call 2023 - Pilot Lines
- Chips-JU Call 2024

Idea presentation

EC'S Brokerage 2024

- This idea will be presented as poster
- This idea will be presented as presentation
- Cyber intelligence · Distributed computing · Stream processing · Middleware · Trusted computing · Quantum systems · Hybrid-clouds · 5G · Cross border security

Request to join idea

Contact

Muhammed Akif AGCA  
TOBB ECONOMY AND TECHNOLOGY UNIVERSITY (TOBB ETU)  
Turkey

Uploaded documents

- TrustLine\_Poster
- TrustLine\_Poster

Project idea pitch video

No project idea pitch video uploaded.

Comments

Comment

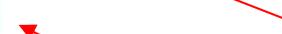
LEAVE A MESSAGE...



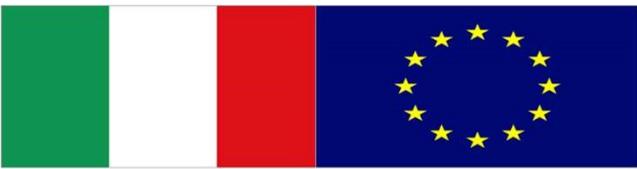
Contact Person



Poster/Presentation if any



Video Pitch if any



# ECS Brokerage Event 2025



- All the 44 Project Ideas are available on the Collaboration Tool. Among them:
  - 32 Ideas have inserted a poster
  - 24 Ideas have inserted a presentation
  - 20 have inserted both
- For detailed info you can download all the material from the ECS Tool <https://ecscollaborationtool.eu/>



# Proposals by SRIA topics



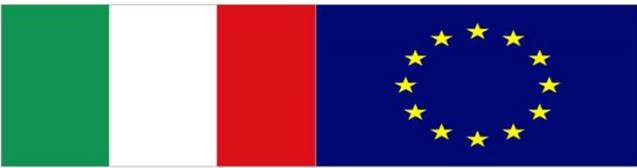
Foundational Technology Layers			Cross Sectional Technology			ECS Key Application Areas		
1.1	Process Technology, Equipment, Materials & Manufacturing for ECS	16	2.1	Edge computing and Embedded AI	14	3.1	Mobility	10
1.2	Components, Modules and System Integration	20	2.2	Connectivity	7	3.2	Energy	10
1.3	Embedded Software and Beyond	8	2.3	Architecture and Design Methods and Tools	10	3.3	Digital Industry	13
1.4	System of Systems	7	2.4	Quality, Reliability Safety and Cybersecurity	5	3.4	Health & Wellbeing	5
						3.5	Agrifood & Resources	5
						3.6	Digital Society	8



# to what to pay attention?



- Novelty of the idea and appropriateness of the in/out expected TRL level
- Adherence to the Focus Topics or to the SRIA25
- Industrial and Academic strenght of the Consortium
- Italian Universities and RTOs cannot join without at least one Large Enterprise or SME
- Only for the newcomers:
  - Presence of other Italian partners to whom to ask for national rules and asking to national cluster coordinator challenges and constraints
  - Knowledge in case of absence of other Italian partners, of all the Italian rules



# Thank you and good luck!

For any further info do not hesitate to get in touch with us:

Livio Baldi

[baldi.livio@gmail.com](mailto:baldi.livio@gmail.com)

Alberto Bianchi

[alberto.bianchi@leonardo.com](mailto:alberto.bianchi@leonardo.com)